

GSM2302

20V N-Channel Enhancement Mode MOSFET

Product Description

The GSM2302 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and high density cell Design for ultra low on-resistance. This device is suitable for use as a load switch or in PWM applications.

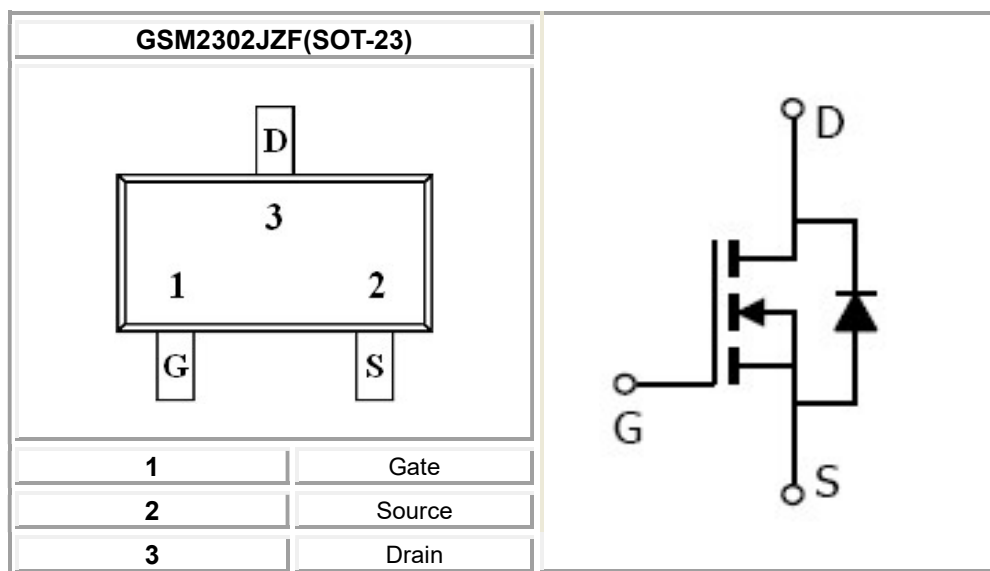
Features

- 20V/2.5A, $R_{DS(ON)}=46m\Omega@V_{GS}=4.5V$
- $R_{DS(ON)}=61m\Omega@V_{GS}=2.5V$
- High power and current handling capability
- SOT-23 package design

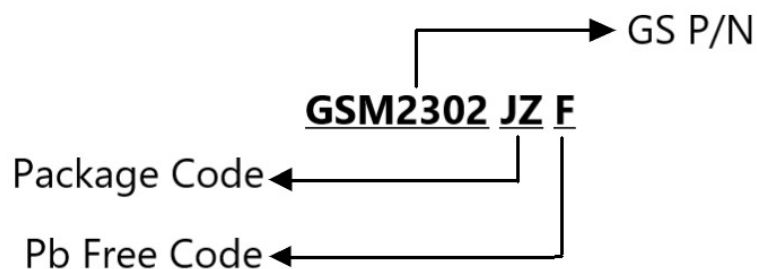
Applications

- PWM Applications
- Load Switch

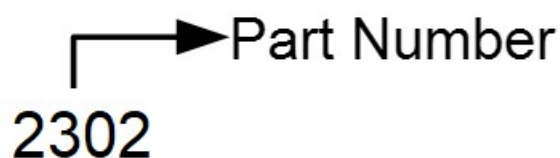
Packages & Pin Assignments



Ordering Information



Marking Information



Part Number	Package	Part Marking
GSM2302JZF	SOT-23	2302

Absolute Maximum Ratings

T_A=25°C unless otherwise noted

Symbol	Parameter		Limit	Unit
V _{DSS}	Drain-Source Voltage		20	V
V _{GSS}	Gate –Source Voltage		±12	V
I _D	Continuous Drain Current(T _J =150°C) ¹	T _A =25°C	2.5	A
		T _A =70°C	2.0	
I _{DM}	Pulsed Drain Curren ²		10	A
I _S	Continuous source current (diode conduction) ¹		0.6	A
P _D	Power Dissipation ¹	T _A =25°C	0.71	W
		T _A =70°C	0.46	W/
T _J	Operating Junction Temperature Range		-55 to 150	°C
T _{STG}	Storage Temperature Range		-55 to 150	°C
R _{θJA}	Thermal Resistance - Junction to Ambient ¹		175	°C/W

Notes

1. Surface mounted on 1" x 1" FR4 board
2. Pulse width limited by maximum junction temperature

Electrical Characteristics

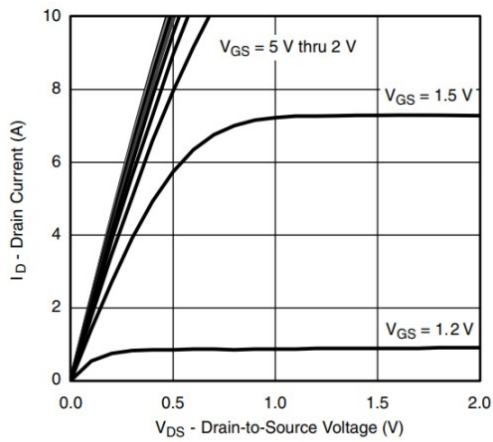
T_A=25°C unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ	Max.	Unit
Static						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	20			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	0.5	0.65	1.0	
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±12V			±100	nA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =20V, V _{GS} =0V			1	uA
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =4.5V, I _D =2.5A		46	60	mΩ
		V _{GS} =2.5V, I _D =1A		61	85	
g _{FS}	Forward Transconductance	V _{DS} =5V, I _S =2A		5		S
V _{SD}	Diode Forward Voltage	I _S =2.5A, V _{GS} =0V		0.76	1.16	V
Dynamic						
Q _g	Total Gate Charge ^{2,3}	V _{DS} =10V, V _{GS} =4.5V I _D =2.5A		3.5		nC
Q _{gs}	Gate-Source Charge ^{2,3}			0.6		
Q _{gd}	Gate-Drain Charge ^{2,3}			0.45		
C _{iss}	Input Capacitance	V _{DS} =10V, V _{GS} =0V f=1MHz		308		pF
C _{oss}	Output Capacitance			52		
C _{rss}	Reverse Transfer Capacitance			27		
t _{d(on)}	Turn-On Time ^{2,3}	V _{DD} =10V, R _L =4Ω, V _{GS} =4.5V, R _G =6Ω		8		ns
t _r				27		
t _{d(off)}	Turn-Off Time ^{2,3}			20		
t _f				17		

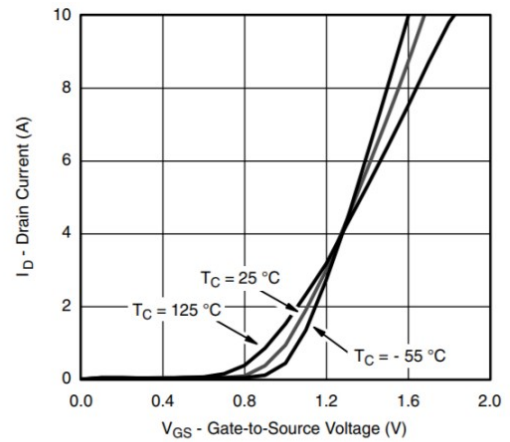
Note :

1. Pulse test: Pulse width ≤ 300 μs, duty cycle ≤ 2 %
2. Guaranteed by design, not subject to production testing

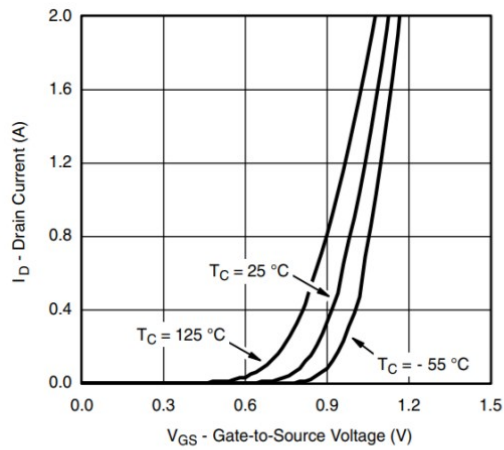
Typical Performance Characteristics



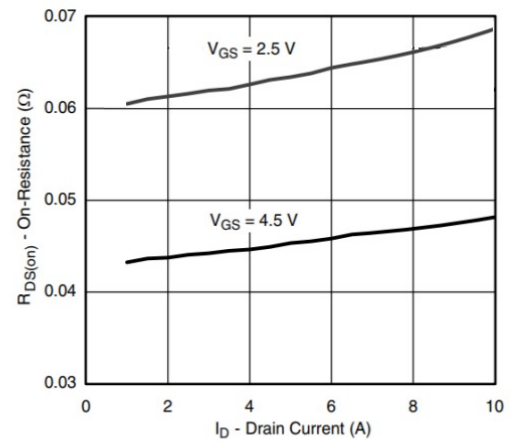
Output Characteristics



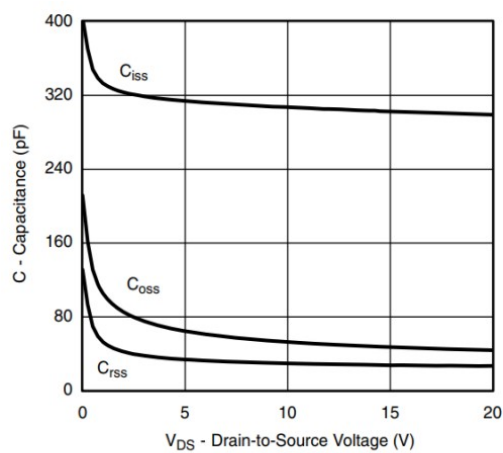
Transfer Characteristics



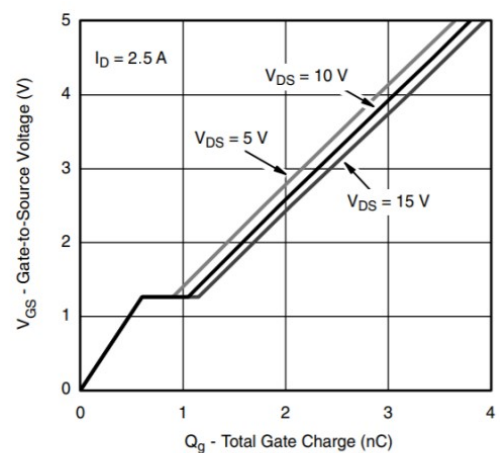
Transfer Characteristics



On-Resistance vs. Drain Current

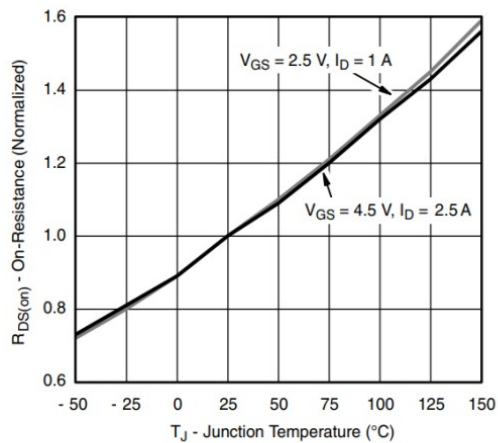


Capacitance

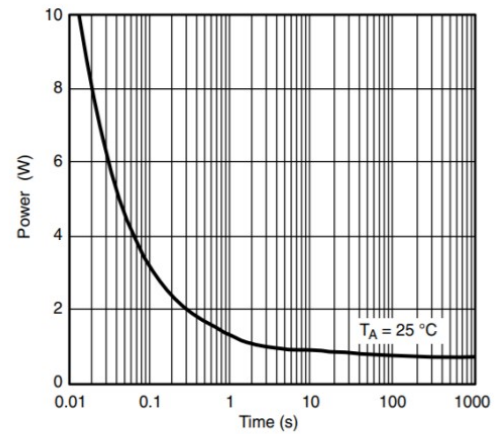


Gate Charge

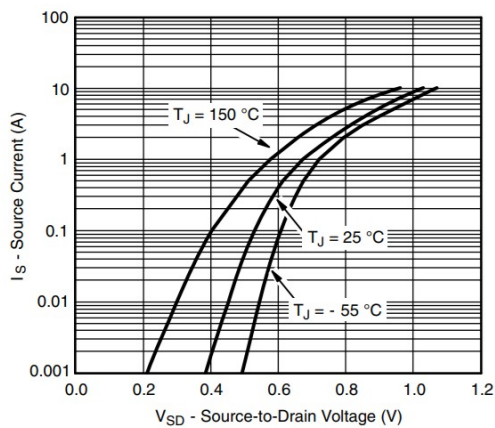
Typical Performance Characteristics (continue)



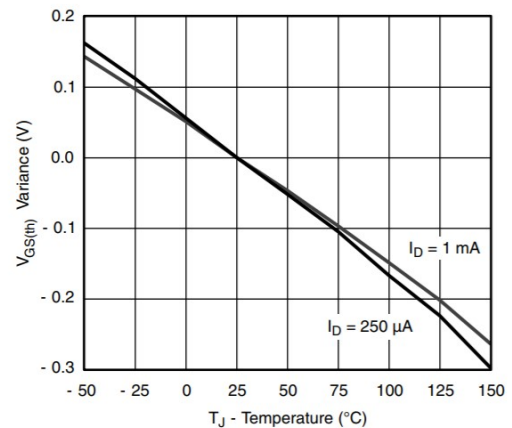
On-Resistance vs. Junction Temperature



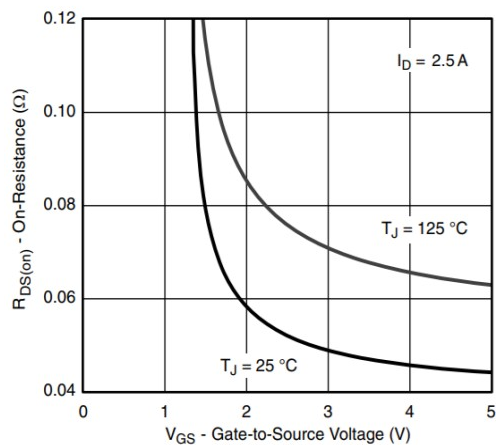
Single Pulse Power



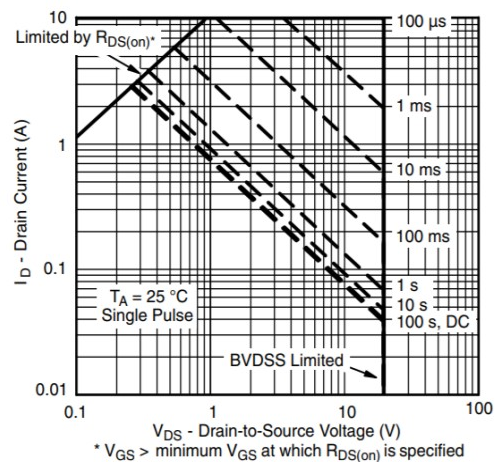
Source-Drain Diode Forward Voltage



Threshold Voltage



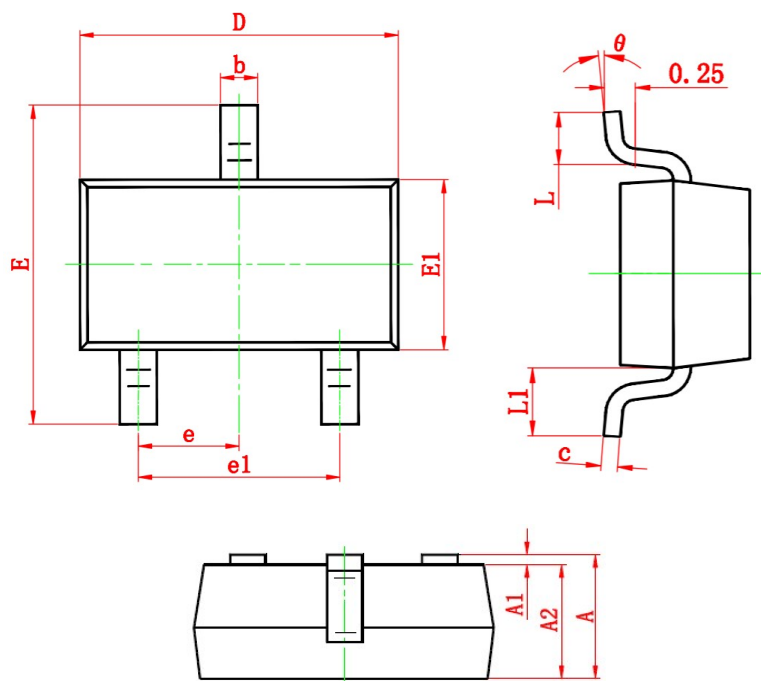
On-Resistance vs. Gate-to-Source Voltage



Safe Operating Area, Junction-to-Ambient

Package Dimension

SOT-23



Dimensions

Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.900	1.500	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	2.250	2.550	0.047	0.055
E1	1.200	1.400	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.300	0.500	0.012	0.020
L1	0.550 REF		0.022 REF	
θ	0°	8°	0°	6°

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